

## 1.0A, 500V N-CHANNEL POWER MOSFET

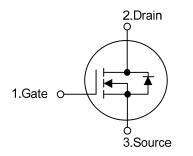
#### DESCRIPTION

The UTC **1N50-TA** is a high voltage MOSFET and is designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and have a high rugged avalanche characteristics. This power MOSFET is usually used at high speed switching applications in power supplies, PWM motor controls, high efficient DC to DC converters and bridge circuits.

#### FEATURES

- \*  $R_{DS(ON)}$  < 10.5 $\Omega$  @  $V_{GS}$ =10V,  $I_{D}$ =0.5A
- \* Fast switching capability
- \* Avalanche energy specified
- \* Improved dv/dt capability, high ruggedness

#### SYMBOL



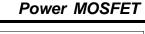
#### ORDERING INFORMATION

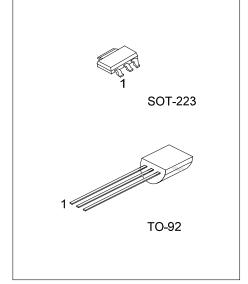
Ordering Number			Daakaga	Pin Assignment			Dooking	
	Lead Free	Halogen Free	Package	1	2	3	Packing	
	-	1N50G-AA3-R	SOT-223	G	D	S	Tape Reel	
	1N50L-T92-B	1N50G-T92-B	TO-92	G	D	S	Tape Box	
	1N50L-T92-K	1N50G-T92-K	TO-92	G	D	S	Bulk	
Note:	Pin Assignment: G: C	Gate D: Drain S: Source	9					

 1N50G-AA3-R
 (1)Packing Type
 (1) R: Tape Reel, B: Tape Box, K: Bulk

 (2)Package Type
 (2)Package Type
 (2)AA3: SOT-223, T92: TO-92

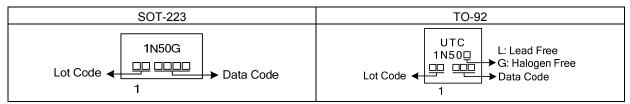
 (3)Green Package
 (3) L: Lead Free, G: Halogen Free and Lead Free





### Power MOSFET

#### MARKING





#### ■ **ABSOLUTE MAXIMUM RATINGS** (T<sub>c</sub> = 25°C, unless otherwise specified)

PARAMETER		SYMBOL	SYMBOL RATINGS	
Drain-Source Voltage		V <sub>DSS</sub>	500	V
Gate-Source Voltage		V <sub>GSS</sub>	±30	V
Drain Current	Continuous	ID	1.0	А
	Pulsed (Note 2)	I <sub>DM</sub>	4.0	А
Avalanche Energy	Single Pulsed (Note 3)	E <sub>AS</sub>	10	mJ
Peak Diode Recovery dv/	ak Diode Recovery dv/dt (Note 4)		5.0	V/ns
Dowor Dissinction	SOT-223	D	7.8	W
Power Dissipation	TO-92	P <sub>D</sub>	1.42	W
Junction Temperature		TJ	+150	°C
Storage Temperature		T <sub>STG</sub>	-55 ~ +150	°C

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. L = 10mH, I<sub>AS</sub> = 1.4A, V<sub>DD</sub> = 50V, R<sub>G</sub> = 25 $\Omega$ , Starting T<sub>J</sub> = 25°C

3. I\_{SD} \le 1.0A, di/dt \le 200A/\mu s, V\_{DD} \le BV\_{DSS}, Starting T\_J = 25°C

#### THERMAL DATA

PARA	METER	SYMBOL	RATINGS	UNIT	
Junction to Ambient	SOT-223	0	150	°C/W	
Junction to Ambient	TO-92	θ <sub>JA</sub>	180	°C/W	
lunction to Coop	SOT-223	0	16	°C/W	
Junction to Case	TO-92	θ <sub>JC</sub>	88	°C/W	



#### ■ ELECTRICAL CHARACTERISTICS (T<sub>J</sub> = 25°C, unless otherwise specified)

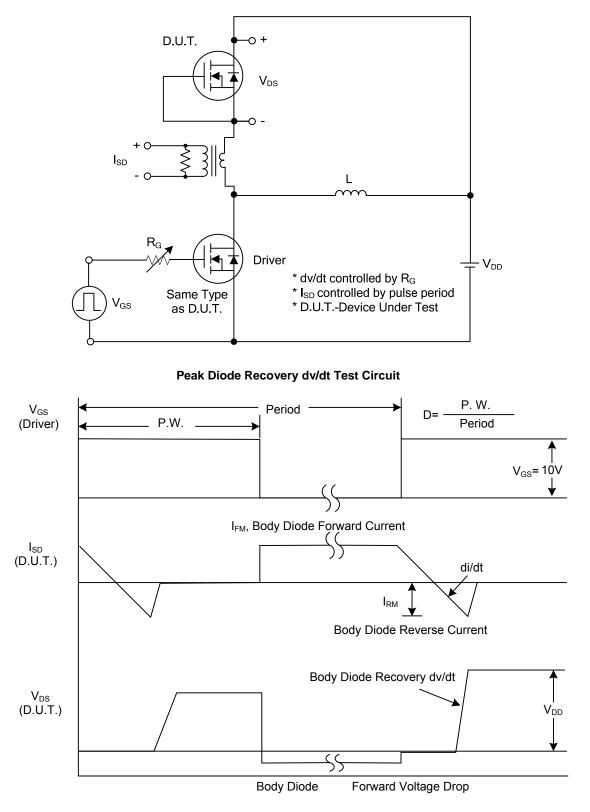
PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
OFF CHARACTERISTICS							-
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250µA	500			V	
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =500V, V <sub>GS</sub> =0V			1	μA	
Gate-Source Leakage Current	Forward	- I <sub>GSS</sub>	V <sub>GS</sub> =30V, V <sub>DS</sub> =0V			100	nA
R	everse		V <sub>GS</sub> =-30V, V <sub>DS</sub> =0V			-100	nA
ON CHARACTERISTICS							-
Gate Threshold Voltage		V <sub>GS(TH)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250µA	3.0		5.0	V
Static Drain-Source On-State Resist	tance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =0.5A			10.5	Ω
DYNAMIC CHARACTERISTICS							
Input Capacitance		CISS			86		рF
Output Capacitance		C <sub>OSS</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =25V, f=1MHz		17		рF
Reverse Transfer Capacitance	C <sub>RSS</sub>			5.0		рF	
SWITCHING CHARACTERISTICS							
Total Gate Charge (Note 1)		$Q_{G}$	V <sub>DS</sub> =30V, V <sub>GS</sub> =10V, I <sub>D</sub> =0.5A,		8.8		nC
Gate to Source Charge		$Q_{GS}$	$I_{G}$ =100µA (Note 1, 2)		1.2		nC
Gate to Drain Charge		$Q_{GD}$	$10^{-100}\mu$ A (1000 1, 2)		1.3		nC
Turn-on Delay Time (Note 1)		t <sub>D(ON)</sub>			32		ns
Rise Time		t <sub>R</sub>	V <sub>DD</sub> =30V, V <sub>GS</sub> =10V, I <sub>D</sub> =0.5A,		10		ns
Turn-off Delay Time		t <sub>D(OFF)</sub>	R <sub>G</sub> =25Ω (Note 1, 2)		33		ns
Fall-Time		t <sub>F</sub>			17		ns
SOURCE- DRAIN DIODE RATINGS	S AND CHA	ARACTERIS	TICS				
Maximum Body-Diode Pulsed Current		ls				1.0	Α
Drain-Source Diode Forward Voltage (Note 1)		I <sub>SM</sub>				4.0	Α
Maximum Body-Diode Continuous Current		$V_{SD}$	I <sub>S</sub> =0.3A, V <sub>GS</sub> =0V			1.4	V
Reverse Recovery Time (Note 1)		trr	I <sub>S</sub> =1.0A, V <sub>GS</sub> =0V,		200		ns
Reverse Recovery Charge	Qrr	dI <sub>F</sub> /dt=100A/µs		0.4		μC	

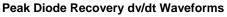
Notes: 1. Pulse Test: Pulse width  $\leq$  300µs, Duty cycle  $\leq$  2%.

2. Essentially independent of operating temperature.



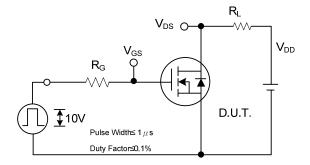
### TEST CIRCUITS AND WAVEFORMS



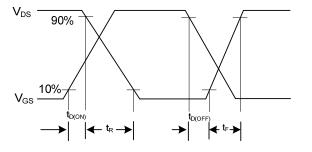




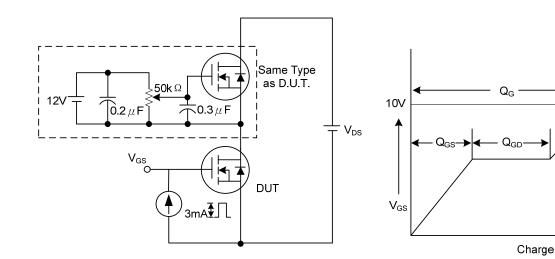
#### ■ TEST CIRCUITS AND WAVEFORMS (Cont.)



**Switching Test Circuit** 

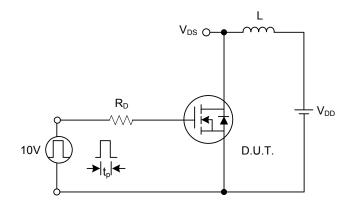


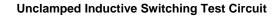
Switching Waveforms

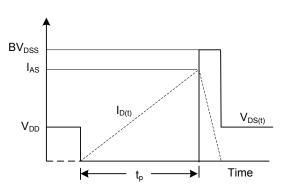


**Gate Charge Test Circuit** 

**Gate Charge Waveform** 







**Unclamped Inductive Switching Waveforms** 



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